PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHUNG-YU LEE	08/19/2013
CHUN-CHANG CHEN	08/19/2013

RECEIVING PARTY DATA

Name:	SHIN ZU SHING CO., LTD.	
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City:	NEW TAIPEI CITY 238	
State/Country:	TAIWAN	
Postal Code:	R.O.C.	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14053776

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	102-603-00347.IUS
NAME OF SUBMITTER:	ALAN D. KAMRATH
Signature:	/Alan D. Kamrath/
Date:	10/15/2013 PATENT

502532257 REEL: 031404 FRAME: 0182

OP \$40.00 14053776

This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

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PATENT REEL: 031404 FRAME: 0183

ASSIGNMENT/DECLARATION FOR PATENT APPLICATION

WHEREAS, as a below named inventor, I hereby declare that:

My residence, mailing address, and citizenship are as stated below next to my name. I believe I am the original inventor (if only one name is listed below) or an original joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Phase-locked pivot as	ssembly
the specification of which is attached hereto.	
The above application was made or authorized by m	ne.
WHEREAS SHIN ZU SHING CO., LTD. of	Taiwan, R.O.C.
herein referred to as "Assignee" whose mailing address is	No. 174, Jyunving St., Shulin Dist.,
New Taipei City 238, Taiwan (R.O.C.)	
is desirous of acquiring the entire right, title and interest in	and to said invention, and in and to and unde
any and all Letters Patent to be obtained thereon.	

NOW, THEREFORE, for and in consideration of one Dollar (\$1.00) and other good and valuable considerations, the receipt of which is hereby acknowledged, I/We the inventor(s) have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the Assignee, its successors and assigns the entire right, title and interest in and to said invention, said application and the Letters Patent, both foreign and domestic, that may or shall issue, including all of my rights under International Convention, and I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to the Assignee in accordance herewith.

Upon said consideration, I/We do hereby covenant and agree with the said Assignee, its successors and assigns, that I/We will not execute any writing or do any act whatsoever conflicting with these presents, and that I/We or my/our executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights, occurring as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

I hereby acknowledge that any willful false statement made in this declaration is punishable by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Full Name of Sole or First Inventor: LEE, Chung-Yu (Family name: LEE)		
Residence: No. 174, Jyunying St., Shulin Dist., New Taipei City 238, Taiwan (R.O.C.)		
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Country: Taiwan, R.O.C.	Citizenship: Taiwan, R.O.C.	
Inventor's Signature: Lee Chung I	Date: August 19, 2013	
Additional inventors are being named on the following page(s) of this sheet		

PATENT REEL: 031404 FRAME: 0184

Full Name of Joint Inventor (if any): CHEN,	Chun-Chang (Family name: CHEN)
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Inventor's Chen, Chun-chang	Date: August 19. 2013